

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	(wafer or semiconductor or substrate or workpiece) and (motor or drive) same ("ball guide" and "ball screw" and "ball block")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:03
L3	3	(wafer or semiconductor or substrate or workpiece) and (motor or drive) and ("ball guide" and "ball screw" and "ball block")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 09:59
L4	3	(motor or drive) and ("ball guide" and "ball screw" and "ball block")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 09:59
L5	3	(wafer or semiconductor or substrate or workpiece) and (motor or drive) same ("ball screw" and "ball block")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:04
L6	10803	(wafer or semiconductor or substrate or workpiece) and (motor or drive) same (screw and block)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:05
L7	928	(wafer or semiconductor or substrate or workpiece) and (motor or drive) near10 (screw near10 block)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:05
L8	17	(wafer or semiconductor or substrate or workpiece) and (motor or drive) near10 (screw near10 block) and "134"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:10
L9	196	(wafer or semiconductor or substrate or workpiece) same (motor or drive) near10 (screw near10 block)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 10:10

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L25	1	"2002281628"	JPO	OR	ON	2006/09/29 14:42
S1	181	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) near10 (holder or support) near10 (groove or drain\$3)	US-PGPUB; USPAT	OR	ON	2006/09/21 11:55
S2	249	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) near10 (holder or support) near10 (groove or drain\$3 or hole)	US-PGPUB; USPAT	OR	ON	2006/05/18 19:11
S3	29	"6115867" "6148463" "6357457"	US-PGPUB; USPAT	OR	ON	2006/05/19 09:13
S4	16146	(wafer or semiconductor or substrate or workpiece) and plate near10 (nozzle or spray\$3)	US-PGPUB; USPAT	OR	ON	2006/05/19 09:14
S5	381	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) and plate near10 (nozzle or spray\$3)	US-PGPUB; USPAT	OR	ON	2006/09/28 17:26
S6	217	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3)	US-PGPUB; USPAT	OR	ON	2006/05/19 09:15
S7	27	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3) near10 (plurality or array or group or multiple)	US-PGPUB; USPAT	OR	ON	2006/05/19 09:28
S8	0	(wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3) near10 (plurality or array or group or multiple) near10 ((top and bottom) or (above and below) or (first near5 surface and second near5 surface)) near15 (gas and liquid) and (nozzle or spray) near10 (slant\$3 or inclin\$3 or slop\$3) and (motor or driv\$3) near10 (rotat\$3 and (hold\$3 or arm))	US-PGPUB; USPAT	OR	ON	2006/05/19 09:35

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S9	0	(wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3) near10 (plurality or array or group or multiple) near15 (gas and liquid) and (nozzle or spray) near10 (slant\$3 or inclin\$3 or slop\$3) and (motor or driv\$3) near10 (rotat\$3 and (hold\$3 or arm))	US-PGPUB; USPAT	OR	ON	2006/05/19 09:35
S10	0	(wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3) near10 (plurality or array or group or multiple) near15 (gas and liquid) and (motor or driv\$3) near10 (rotat\$3 and (hold\$3 or arm))	US-PGPUB; USPAT	OR	ON	2006/09/28 17:49
S11	7	(wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plurality or array or group or multiple) near15 (gas and liquid) and (motor or driv\$3) near10 (rotat\$3 and (hold\$3 or arm))	US-PGPUB; USPAT	OR	ON	2006/06/21 17:06
S12	13	(wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plat\$3) near15 (gas and liquid) and (motor or driv\$3) near10 (rotat\$3 and (hold\$3 or arm))	US-PGPUB; USPAT	OR	ON	2006/05/19 09:55
S13	6	(wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plat\$3) near15 (gas and liquid) same ((top near10 bottom) or (above near10 below) or (upper near10 lower))	US-PGPUB; USPAT	OR	ON	2006/05/19 10:16
S14	592	(wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plat\$3) same ((top near10 bottom) or (above near10 below) or (upper near10 lower))	US-PGPUB; USPAT	OR	ON	2006/09/28 17:49
S15	274	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plat\$3)	US-PGPUB; USPAT	OR	ON	2006/05/19 11:54
S16	0	104/902.ccls.	US-PGPUB; USPAT	OR	ON	2006/06/21 17:06

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S17	1865	134/902.ccls.	US-PGPUB; USPAT	OR	ON	2006/06/21 17:06
S18	1218	S17 and (nozzle or spray\$3)	US-PGPUB; USPAT	OR	ON	2006/06/21 17:06
S19	335	S18 and (134/151,153,198.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/21 17:12
S20	3	US-6115867-\$.DID. OR US-6148463-\$.DID. OR US-6357457-\$.DID.	US-PGPUB; USPAT	OR	ON	2006/09/28 18:01
S21	42	"5248380"	US-PGPUB; USPAT	OR	ON	2006/09/21 16:51
S22	55	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) and plate near10 (nozzle or spray\$3) near10 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/09/28 17:26
S23	31	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same plate near10 (nozzle or spray\$3) near10 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/09/28 17:26
S24	26	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same (nozzle or spray\$3) near10 (plat\$3) same ((top near10 bottom) or (above near10 below) or (upper near10 lower))	US-PGPUB; USPAT	OR	ON	2006/09/28 17:50
S25	29	plurality near5 nozzle near10 peripheral and "134"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2006/09/28 18:02
S26	1467	nozzle near10 center and nozzle near10 (edge or periph\$3)	US-PGPUB	OR	ON	2006/09/28 18:03
S27	98	nozzle near10 center and nozzle near10 (edge or periph\$3) and "134"/\$.ccls.	US-PGPUB	OR	ON	2006/09/28 18:08
S28	389	"134"/\$.ccls. and plurality near6 nozzle	US-PGPUB	OR	ON	2006/09/28 18:08
S29	201	"134"/\$.ccls. and plurality near6 nozzle and (wafer or semiconductor or substrate)	US-PGPUB	OR	ON	2006/09/28 18:25
S30	0	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same nozzle near10 (diameter) near8 (decreas\$3 or smaller or smaller) near10 (peripher\$3 or outer or edge)	US-PGPUB	OR	ON	2006/09/28 18:30

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S31	25	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) and nozzle same (diameter) near8 (decreas\$3 or smaller or smaller)	US-PGPUB	OR	ON	2006/09/28 18:31
S32	17	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller)	US-PGPUB	OR	ON	2006/09/28 18:42
S33	235	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller)	US-PGPUB	OR	ON	2006/09/28 18:42
S34	19	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller) near10 (edge or periphery or outer or peripher\$3 or outside)	US-PGPUB	OR	ON	2006/09/28 18:42
S35	785	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 18:42
S36	102	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller) near10 (edge or periphery or outer or peripher\$3 or outside)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 19:16
S37	52	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 19:16
S38	197	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (decreas\$3 or smaller or smaller or increas\$3 or larger) near10 (edge or periphery or outer or peripher\$3 or outside)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 19:33

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S39	1005	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (increas\$3 or larger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 19:33
S40	64	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (increas\$3 or larger) and "134"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 20:04
S41	32	(wafer or semiconductor or substrate or workpiece) same nozzle same (diameter) near8 (increas\$3 or larger) and "134"/902.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 19:33
S42	361	(wafer or semiconductor or substrate or workpiece) same nozzle near10 (angle or inclin\$4 or tilt\$3 or slant\$3 or declin\$4) and "134"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 20:07
S43	144	(wafer or semiconductor or substrate or workpiece) same nozzle near10 (gas) near10 (plurality or several or multiple) and nozzle near10 (liquid or fluid or chemical) near10 (plurality or several or multiple)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 20:10
S44	105	(wafer or semiconductor or substrate or workpiece) same nozzle near10 (gas) near10 (top or front) and nozzle near10 (gas) near10 (back or bottom)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 20:30
S45	8	"6874516"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/28 20:22
S46	114	(wafer or semiconductor or substrate or workpiece) same plate near10 (bottom or below or base or lower) near10 (rotat\$3) near10 (motor or drive) and plate near10 (top or above or upper) near10 (rotat\$3) near10 (drive or motor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2006/09/29 09:53